

1.0 INTRODUCTION

This drawing describes the requirements for procuring the unpackaged integrated circuit die used in the manufacture of P/N MC10137, a Universal Decade Counter. All changes and/or substitutions to the procured parts are subject to prior approval by Interpoint. This document shall be used with GEN-008.

2.0 APPLICABLE DOCUMENTS

GEN-008 Integrated Circuit Dice

3.0 REQUIREMENTS

3.1 Mechanical/Physical Characteristics

Each die shall be configured per Figure 1 and Figure 2.

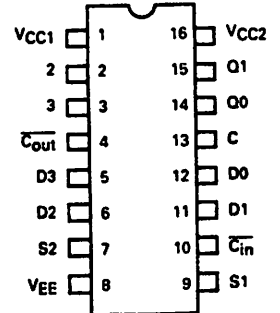
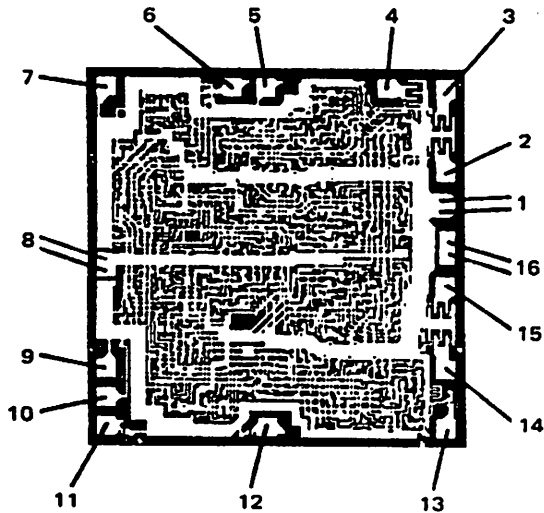


FIGURE 1
CONNECTION DIAGRAM



- NOTES: 1. Motorola
 2. Die size .090 x .091 ± .005
 3. Metallization - Topside: Al; Backside (Vee): Au or Si

FIGURE 2 - DIE CONFIGURATION

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interpoint

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SIZE A	CAGE NO. 50821	DRAWING NO. 85290	REV A
SCALE		SHEET 2 OF 3	